



# MVD SPD



*Sezione di Torino*

## Status report of the pixel detector readout electronics



# Performances - 1



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Parameter	Current value	Other proposal	Status
Pixel size	100 $\mu\text{m} \times 100 \mu\text{m}$		Fixed
Chip active area	10 mm $\times$ 10 mm	11.4 mm $\times$ 11.6 mm	To be fixed
dE/dx method	Time over Threshold		Fixed
Max input charge	100 fC		Fixed
Clock	50 MHz	100,125,150 MHz	To be fixed
Time resolution	5.77 ns rms @ 50 MHz	2.31 ns rms @ 125 MHz	To be fixed
Max event rate	12.3 MHz/cm <sup>2</sup>	Ongoing simulations	To be fixed
Data rate per chip	615 Mb/s	815 Mb/s	To be fixed



## Performances - 2



Parameter	Current value	Other proposal	Status
Analog gain	40 mV/fC		~ Fixed
ToT gain	180 ns/fC	72 ns/fC	To be fixed
Max ToT	18 $\mu$ s	7.2 $\mu$ s	To be fixed
Signal polarity	Either n or p		Fixed
Analogue noise	0.032 fC (200 e-)		~ Fixed
Quantization noise	0.032 fC (200 e-)		~ Fixed
Sensor leakage current	< 50 nA/pixel		
Power consumption	< 750 mW/cm <sup>2</sup>	< 500 mW/cm <sup>2</sup>	To be fixed



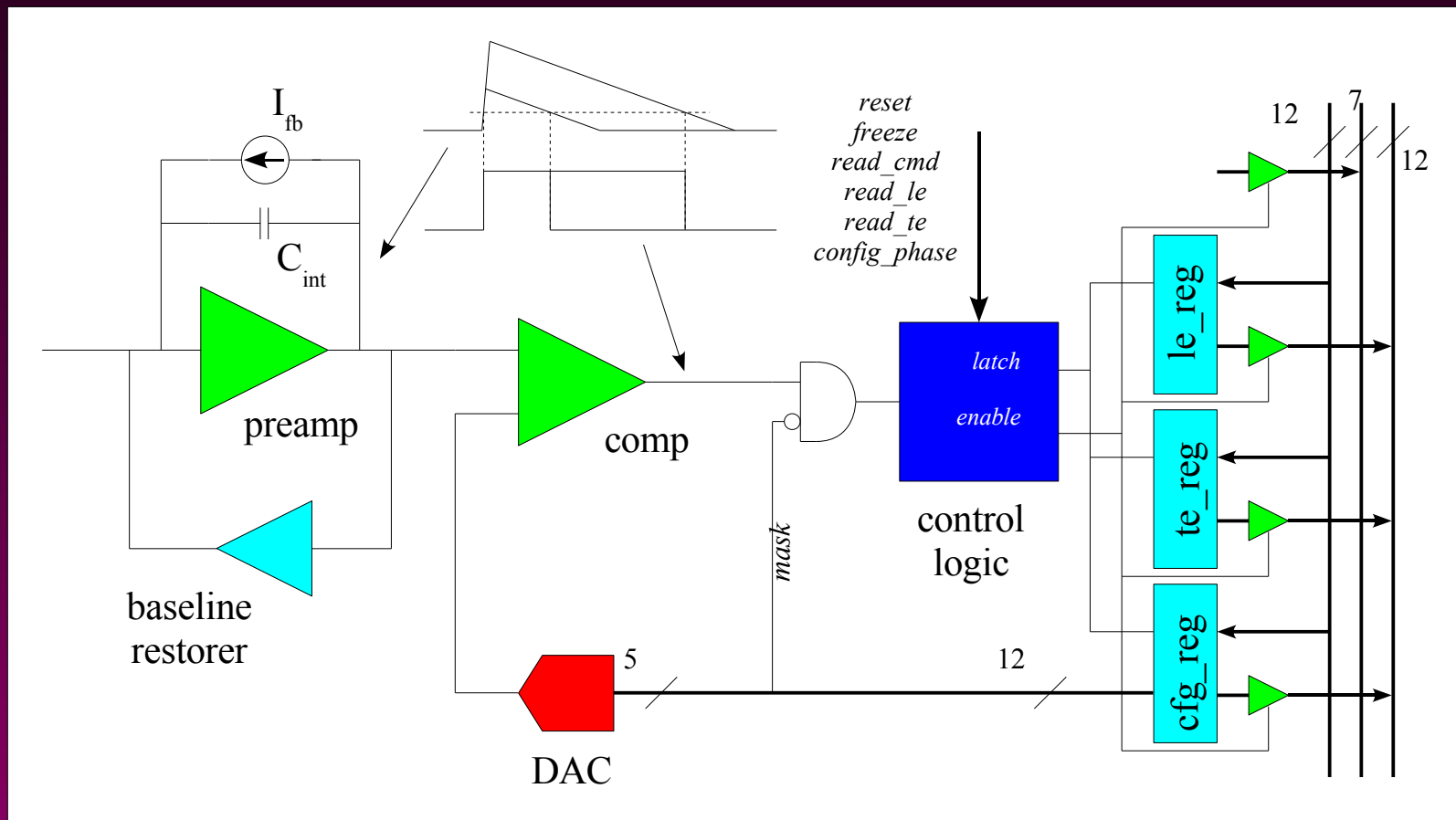
# Performances - 3

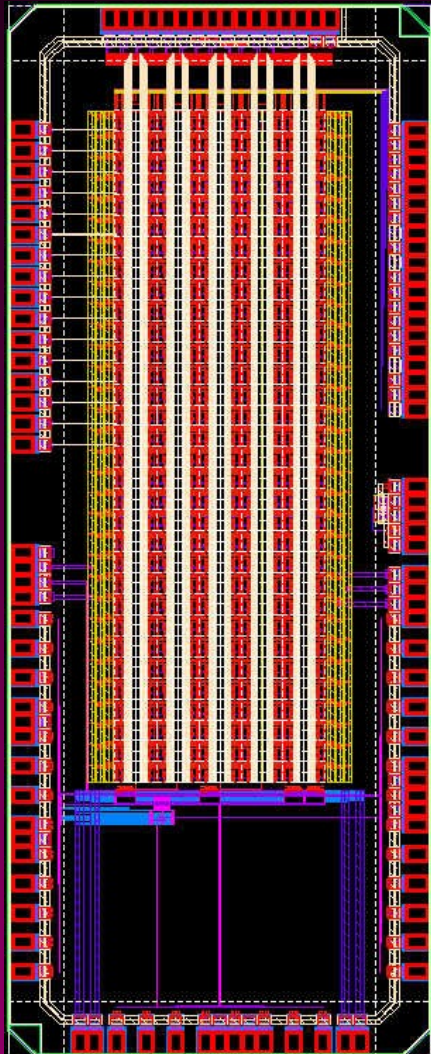


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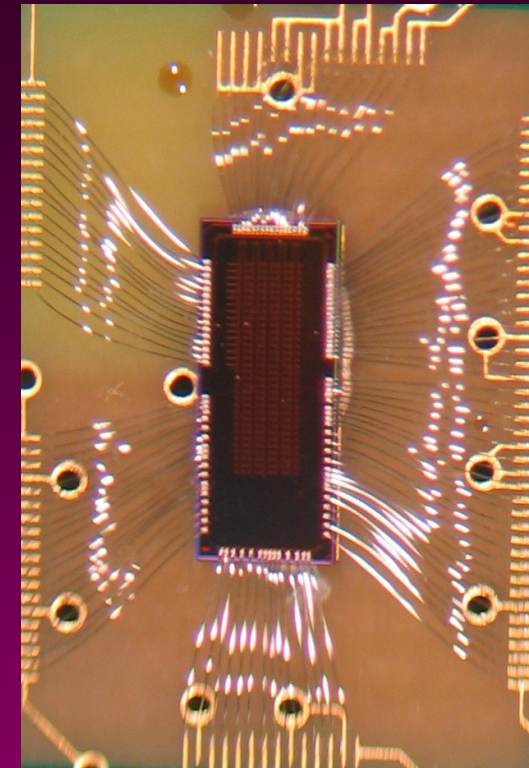
Parameter	Current value	Other proposal	Status
Total Ionizing Dose ( PANDA lifetime )	10 Mrad		To be confirmed
Neutron fluence ( PANDA lifetime )	$5 \cdot 10^{14}$ 1MeV $n_{EQ}/cm^2$		To be confirmed
LET threshold			To be defined
SEU saturation cross section			To be defined

# ToPiX pixel cell





- Full pixel cell ( analogue + digital )
- Two folded columns with 128 cells
- Two columns with 32 cells
- 5x2 mm<sup>2</sup> die area
- CMOS 0.13 μm LM technology
- Working frequency : 50 MHz
- Dice-based SEU resistant FFs
- Tests :
  - test bench
  - with a sensor and a radiation source
  - TID and SEU





# ToPiX upgrade - 1



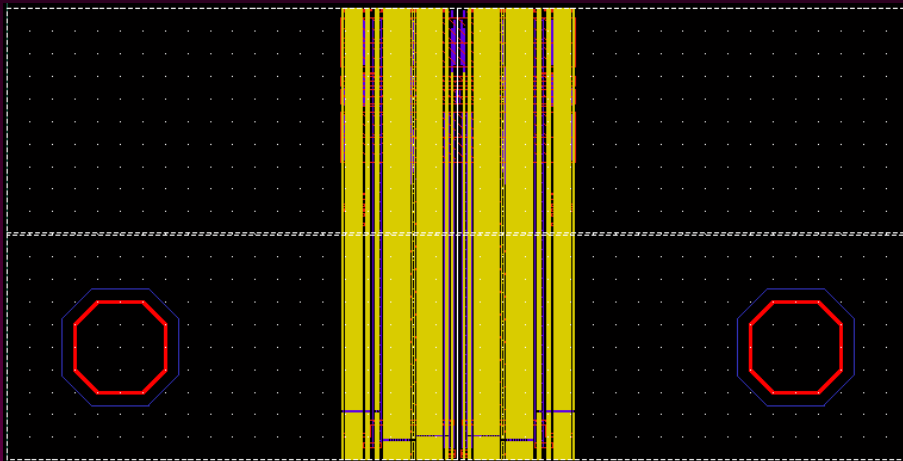
- Technology : LM  $\rightarrow$  DM
  - Reason : DM will become the HEP mainstream
  - LM : 6 (thin) + 2 (thick) metal layers
  - DM : 3 (thin) + 2 (thick) + 3 (RF) metal layers
  - bus width increases by a factor of 3÷4
  - shared bus among adjacent columns
  - better power routing ( thicker lines )
  - signal routing is critical



# DM – LM bus comparison



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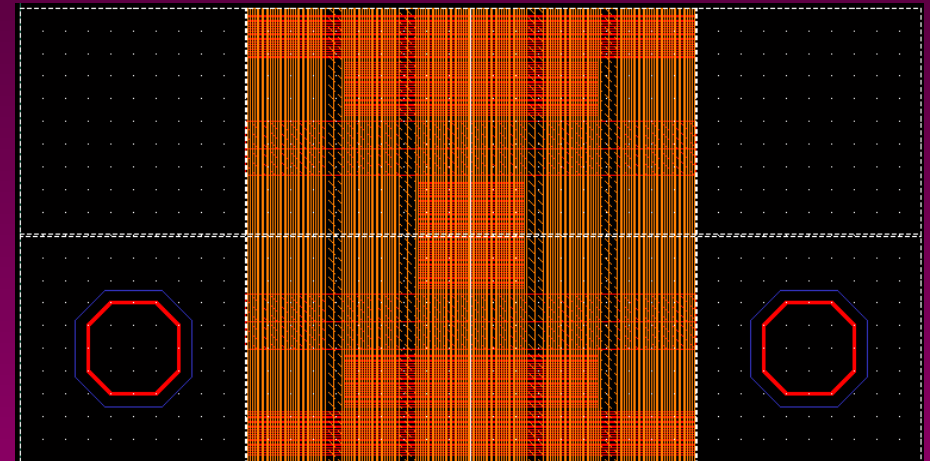


25  $\mu\text{m}$

LM option : bus routing on  
M4 and M6

DM option : bus routing on  
MG only

100  $\mu\text{m}$



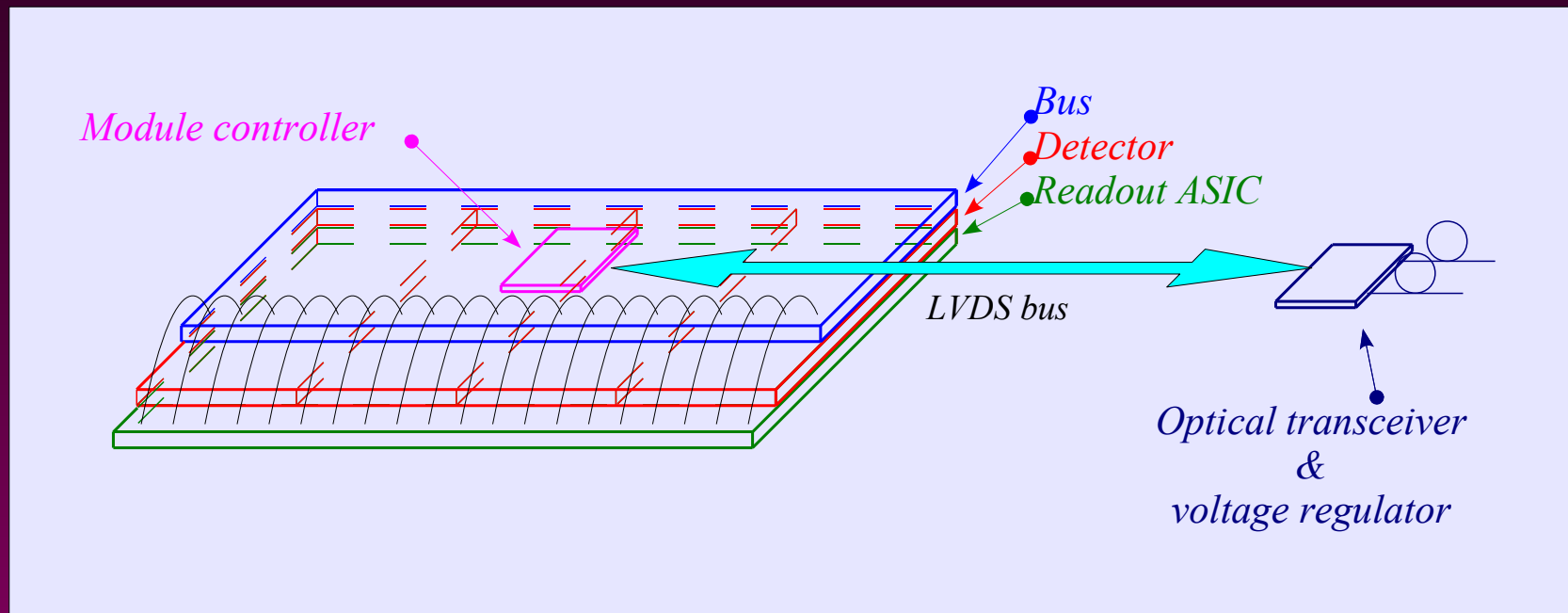




## ToPiX upgrade - 2



- Working frequency : 50 MHz  $\rightarrow$  125 MHz
  - Time stamp bin : 20 ns  $\rightarrow$  8 ns
  - Column readout : 40 ns  $\rightarrow$  32 ns
  - Column drivers and receivers to be redesigned
  - New system simulations required
- SEU protection : DICE cells  $\rightarrow$  triple redundancy
  - Size increase ( estimated :  $\times 1.5 \div 2$  ) in the digital part of the chip  $\rightarrow$  rescaling of the analog part
  - TMR with correction in the configuration register only





# Module concept - 1



- Modules with different size required ( 2,4,5 and 6 F/E chips )
- Up to four 250 Mb/s serial links between ToPiX and module controller.
- 2 or 3 ToPiX chips per module controller
- Module controller to service board : up to  $3 \times 1$  Gb/s electrical links (  $f_{CK} \times 8 \rightarrow$  PLL needed )
- Module controllers can be chained
- Up to 6 F/E ASICs per service board
- Service board to counting room : 3.2 Gb/s optical link



## Module concept - 2



- The module controller functions :
  - Data concentrator
  - Cable reduction
  - Interface between ToPiX and the non-custom circuits
- Service board size and position to be fixed
  - influences on power and signal traces
- Connector position

*Worst nightmare : cable routing*



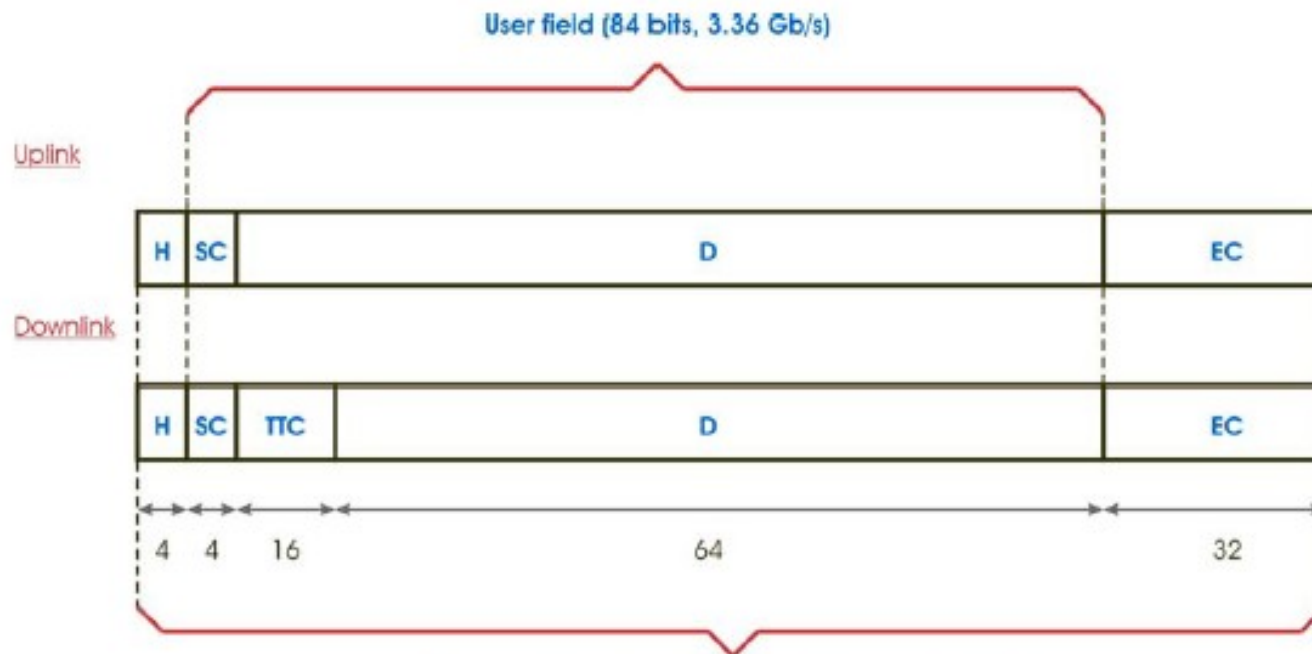


# GBT frame



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## 2.1 Frame structure



Frame: 1 SLHC Clock Cycle (120 bits, 4.8 Gb/s)

H - Header

SC - Slow Control (160 Mb/s)

TTC - Timing Trigger and Control (640 Mb/s)

D - Data (2.56 Gb/s)

EC - Error correction



# Conclusions



- A ToPiX v2 prototype has been designed and tested with good results, *but...*
- *...due to the clock and technology flavour change a major upgrade is required*
- The module controller will require relatively high speed serial links → custom design, contacts with sLHC groups with similar developments for building blocks sharing
- Position of the service board to be fixed – ideally as close as possible to the module
- Existing (GOL) or under development (GBT) rad-hard transceiver for the electrical – optical connection